

OCTOBER 2018/IN-SEM (T1)

S. Y. B. TECH. (PROGRAM) (SEMESTER - I)

COURSE NAME: Semiconductor Devices and Circuits

COURSE CODE:ETUA21174

(PATTERN 2017)

U218-134 (T1)

Q.NO	Sub Q.NO	Marking Scheme	Marks	Difficulty Level	Cognitive level	CO Mapped
Q1	a)	V _{th} =1.33V and R _{th} =4.44K I _B =15.73μA [2] I _C =0.944 mA [2] V _{CE} = 6.32V [2]	[6]	M	Analysis	CO1
	b)	Explanation of the need of bias stabilization [3] Derivation for stability factor S for voltage divider biasing circuit. [3]	[6]	M	Comprehension	CO1
	c)	Draw h parameter model of CE amplifier [2] state the significance of each parameter. [2]	[4]	L	Comprehension	CO1
OR						
Q2	a)	Compare CE, CB and CC amplifier	[6]	M	Comprehension	CO1
	b)	R _{th} =2.67K V _{th} =4V I _B =61.49μA [2] I _C =3.07mA [2] V _{CE} =5.79 [2]	[6]	H	Analysis	CO1
	c)	Explanation of thermal runaway	[4]	M	Knowledge	CO1
Q3	a)	Av= -6.19 [2] R _i = 1Mohm [2] R _o =3.09K [2]	[6]	H	Analysis	CO2
	b)	g _m =3.33 mS [2] I _D =8.34mA [2]	[4]	M	Analysis	CO2
	c)	Draw neat drain characteristic and transfer characteristic	[4]	L	Comprehension	CO2
OR						

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Q4	a)	$I_D = 1.51 \text{ mA}$ [2] $V_{DS} = 8.63 \text{ V}$ [2] $V_{GS} = -2.26 \text{ V}$ [2]	[6]	M	Analysis	CO2
	b)	Draw the ac equivalent circuit [1] Derive expression for voltage gain: [1] Derive expression for R_i [1] Derive expression for R_o [1]	[4]	L	Analysis	CO2
	c)	Justification for each statement 2M	[4]	M	Comprehension	CO1

October 2018 / IN SEM (T₁)

S.Y. B.Tech (E&TC) Sem. I

Course:- SDC

Course code:- ETUA 21174

(Pattern - 2017)

Q1. a) Data given - $V_{CC} = 12V$, $R_1 = 40k$, $R_2 = 5k$, $R_C = 5k$, $R_E = 1k$
 $\beta = 60$

Solution:- $V_{Th} = \frac{5k\Omega}{(5k + 40k)} \times V_{CC} = \frac{R_2}{R_1 + R_2} \times V_{CC}$

$$\boxed{V_{Th} = 1.33V}$$

$$R_{Th} = R_1 \parallel R_2 = \frac{5 \times 40}{5 + 40} = \underline{4.44k\Omega}$$

Apply KVL to base emitter loop.

$$V_{Th} = I_B R_{Th} + V_{BE} + I_E R_E$$

$$\text{But } I_E = (1 + \beta) I_B = 61 I_B$$

$$\therefore 1.33 = 4.44k \cdot I_B + 0.7 + 61k I_B$$

$$\therefore \boxed{I_B = 15.43 \mu A} \quad \text{-----} [2]$$

$$I_C = \beta I_B = 60 \times 15.43 \times 10^{-6}$$

$$\boxed{I_C = 0.944 \text{ mA}} \quad \text{-----} [2M]$$

$$V_{CE} = V_{CC} - I_C R_C - I_E R_E$$

$$\boxed{V_{CE} = 6.32V} \quad \text{-----} [2M]$$

b) Need of bias-stabilization

Bias stabilization is a process of stabilizing the Q point of the circuit. Hence we need to design biasing circuit which will keep the position of Q point stable on the load line.

Due to increase of temperature following parameters of the transistor will change -

1) V_{BE} 2) β 3) I_{CO}

1) The Base to emitter voltage decreases at a rate of $2.5 \text{ mV}/^\circ\text{C}$ with increase in temp. The base current I_B is increase & it will force I_C to change.

2) $\beta \rightarrow$ The current gain β of transistor is temp. dependent. As $I_C = \beta I_B$.

3) change in I_{CO} i.e. reverse saturation current with temp. increase.

$$I_C = \beta I_B + (1 + \beta) I_{CBO}$$

Derivation for stability factor 'S'

$$S = \frac{\Delta I_C}{\Delta I_{CO}} \mid V_{BE} \text{ \& } \beta \text{ const.}$$

For CE configuration

$$I_C = \beta I_B + I_{CEO} = \beta I_B + (1 + \beta) I_{CBO}$$

$$\Delta I_C = \beta \Delta I_B + (1 + \beta) \Delta I_{CBO}$$

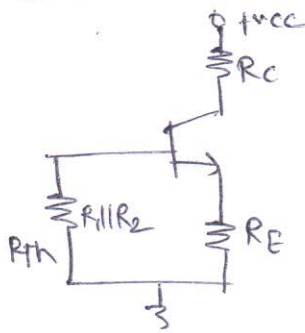
$$1 = \beta \left(\frac{\Delta I_B}{\Delta I_C} \right) + (1 + \beta) \left[\frac{\Delta I_{CBO}}{\Delta I_C} \right]$$

$$1 - \beta \left[\frac{\Delta I_B}{\Delta I_C} \right] = (1 + \beta) \left[\frac{\Delta I_{CBO}}{\Delta I_C} \right]$$

$$\frac{\Delta I_{CBO}}{\Delta I_C} = \frac{1 - \beta (\Delta I_B / \Delta I_C)}{(1 + \beta)}$$

$$\therefore \boxed{S = \frac{1 + \beta}{1 - \beta (\Delta I_B / \Delta I_C)}}$$

consider Thevenin's equivalent circuit.



$$V_{Th} = I_B R_B + V_{BE} + (I_C + I_B) R_E$$

Diff. w.r.t I_C

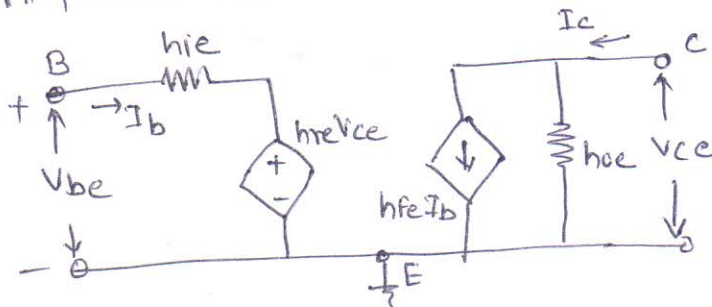
$$\therefore 0 = R_B \cdot \frac{\partial I_B}{\partial I_C} + 0 + R_E + R_E \frac{\partial I_B}{\partial I_C}$$

$$\therefore \boxed{\frac{\partial I_B}{\partial I_C} = \frac{-R_E}{R_B + R_E}}$$

$$\therefore S = \frac{1+B}{1-B \left[\frac{-R_E}{R_B + R_E} \right]}$$

$$\therefore \boxed{S = (1+B) \frac{1 + (R_B/R_E)}{(1+B) + R_B/R_E}}$$

c) H-parameter model of CE amplifier.



1) $h_{ie} = \text{input impedance} = \frac{V_{be}}{I_b} \bigg|_{V_{ce}=0}$

2) $h_{fe} = \text{forward current gain} = \frac{I_C}{I_b} \bigg|_{V_{ce}=0}$

3) $h_{re} = \text{Reverse voltage gain} = \frac{V_{be}}{V_{ce}} \bigg|_{I_b=0}$

4) $h_{oe} = \text{output admittance} = \frac{I_c}{V_{ce}} \bigg|_{I_b=0}$

Q.2 a) compare CE, CB & CC amplifier

Parameters	CE	CB	CC
1) i/p terminal $\rightarrow$	Base	emitter	Base
2) o/p terminal $\rightarrow$	Collector	Collector	Emitter
3) common terminal $\rightarrow$	Emitter	Base	collector
4) i/p resistance $\rightarrow$	Medium	Low	high
5) o/p resistance $\rightarrow$	Medium	High	low
6) current gain $\rightarrow$	High	less than 1	High
7) voltage gain $\rightarrow$	High	High	less than 1
8) Appn. $\rightarrow$	AF voltage Amplifier	Pre-amplifier	Buffer

b) $R_B = R_1 \parallel R_2 = 2.67 \text{ k}\Omega$

$$V_{TH} = \frac{R_2}{R_1 + R_2} \times V_{CC} = 4 \text{ V}$$

$$I_B = \frac{V_{TH} - V_{BE}}{R_B + (1 + \beta) \cdot R_E}$$

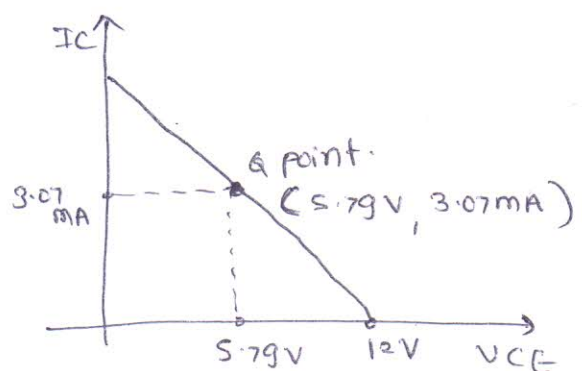
$$I_B = 61.49 \mu\text{A}$$

$$I_{CQ} = \beta I_B = 50 \times 61.49 \times 10^{-6} = 3.07 \text{ mA}$$

$$I_{CQ} = 3.07 \text{ mA}$$

$$V_{CEQ} = V_{CC} - I_{CQ} R_C - I_{EQ} R_E$$

$$V_{CEQ} = 5.79 \text{ V}$$



c) Thermal runaway :-

The rise in collector to base junction takes place due to two reasons -

- 1) Increase of ambient temperature.
- 2) Due to internal heating.

Out of these internal heating process is cumulative as follows

1) An increase in ambient temp. collector current I_C increases the power dissipated in the collector-base junction

2) This will increase the temp of C-B junction.

3) As transistor is NTC device causes increase temp. reduces internal resistance

4) The reduced resistance will increase the I_C further,

This is cumulative process which will finally damage the transistor due to excessive internal heating. This is known as thermal runaway.

Q3 a) For with bypass C_s amplifier using JFET

$$A_v = -g_m(R_D || r_d)$$

$$\therefore g_{m0} = \frac{2I_{DSS}}{V_P} = \frac{32 \text{ mA}}{8 \text{ V}} = 4 \text{ mA/V}$$

$$g_m = \frac{I_{DSS}}{g_{m0}} \left(1 - \frac{V_{GS}}{V_P}\right) = 14 \left(1 - \frac{-4}{-8}\right) = 2 \text{ mA/V}$$

$$\therefore A_v = -6.19$$

$$R_i = R_G = 1 \text{ M}\Omega$$

$$R_o = R_D || r_d = 3.09 \text{ k}\Omega$$

b) Given - $I_{DSS} = 12 \text{ mA}$ $V_p = -6 \text{ V}$, $V_{GS} = -2 \text{ V}$

$$g_{m0} = \frac{2I_{DSS}}{|V_p|} = \frac{24 \text{ mA}}{6} = 4 \text{ mA/V}$$

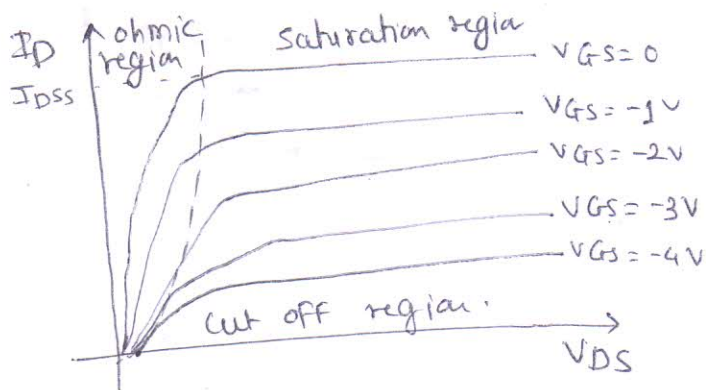
$$g_m = g_{m0} \left(1 - \frac{V_{GS}}{V_p} \right) = 4 \left(1 - \frac{-2}{-6} \right)$$

$$\boxed{g_m = 3.33 \text{ mS}}$$

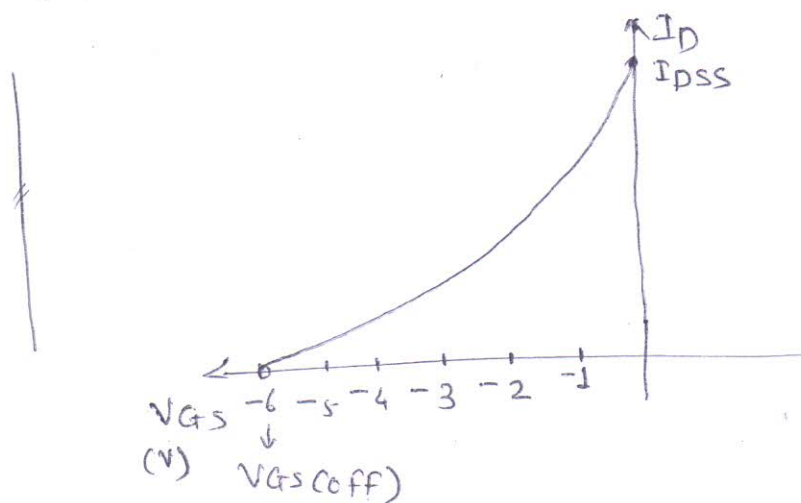
$$I_D = I_{DSS} \left(1 - \frac{V_{GS}}{V_p} \right)^2$$

$$\boxed{I_D = 8.34 \text{ mA}}$$

c) Drain characteristics of n-channel JFET.



Transfer characteristic



Q 4 a) $V_{DD} = 18V$, $R_D = 4.7k$, $R_S = 1.5k$, $R_G = 1M$
 $V_P = -4V$, $I_{DSS} = 8mA$

(9)

$$I_D = I_{DSS} \left(1 - \frac{V_{GS}}{V_P}\right)^2$$

$$V_{GS} = V_G - V_S$$

$$V_{GS} = -I_D \cdot R_S$$

$$\therefore I_D = 8 \times 10^{-3} \left(1 - \frac{-I_D \cdot 1.5k}{-4}\right)^2$$

$$I_D = 8 \times 10^{-3} \left(1 - \frac{1500 \cdot I_D}{4}\right)^2$$

After solving quadratic equation

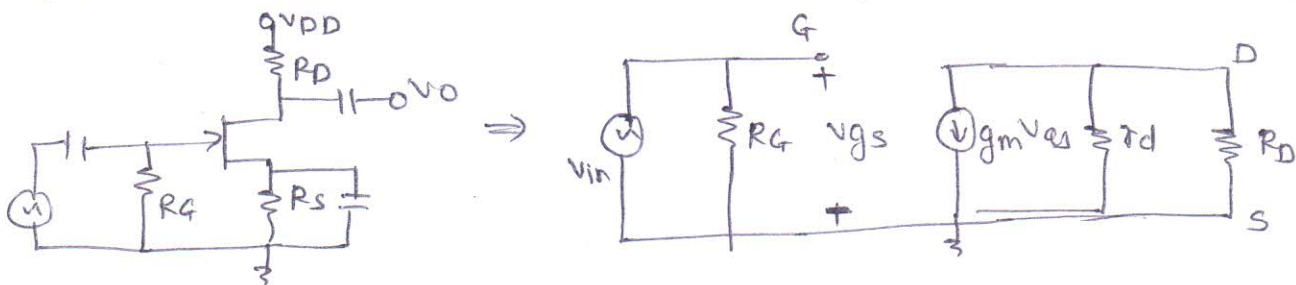
$$I_D = 1.51mA$$

$$V_{DS} = V_{DD} - I_D R_D - I_D R_S$$

$$V_{DS} = 8.63V$$

$$V_{GS} = -I_D R_S = -2.26V$$

b) Derive expression for with bypass (s amplifier).



$$A_v = \frac{V_o}{V_{in}} \quad \text{But } V_o = -g_m V_{gs} (r_d || R_D)$$

$$\& V_{in} = +V_{gs}$$

$$\therefore A_v = \frac{V_o}{V_{in}} = \frac{-g_m V_{gs} (r_d || R_D)}{V_{gs}} = \underline{\underline{-g_m (r_d || R_D)}}$$

$$R_i = R_G = \text{input impedance.}$$

$$R_o = r_d || R_D$$

c) Justify following

i) JFET is a voltage controlled device.

JFET gate current $I_g = 0$ and the voltage between gate to source is used to control current flowing through output terminal. V_{gs} control the drain current

$$g_m = \frac{I_d}{V_{gs}}$$

2) The i/p resistance of JFET is higher than BJT.

According to construction of JFET, its input current is zero. So it having very high i/p resistance. Whereas

BJT is a current controlled device.

$$I_c = \beta I_b$$

As I_c is a function of base current.

output collector current is function of base current.

So its i/p resistance is less.